



Material Content Data Sheet



Sales Product Name		IPG20N06S4L-14A		Issued		24. January 2018		
MA#		MA001663174						
Package		PG-TDSON-8-10		Weight*		99.49 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.690	2.70	2.70	27038	27038
leadframe	non noble metal	iron	7439-89-6	0.046	0.05		467	
	inorganic material	phosphorus	7723-14-0	0.014	0.01		140	
	non noble metal	copper	7440-50-8	46.380	46.62	46.68	466160	466770
wire	non noble metal	aluminium	7429-90-5	0.733	0.74	0.74	7365	7365
encapsulation	organic material	carbon black	1333-86-4	0.089	0.09		891	
	plastics	epoxy resin	-	6.292	6.32		63240	
	inorganic material	silicondioxide	60676-86-0	37.929	38.12	44.53	381219	445350
leadfinish	non noble metal	tin	7440-31-5	1.396	1.40	1.40	14035	14035
plating	inorganic material	phosphorus	7723-14-0	0.001	0.00		14	
	non noble metal	nickel	7440-02-0	0.603	0.61	0.61	6062	6076
solder	noble metal	silver	7440-22-4	0.083	0.08		834	
	non noble metal	tin	7440-31-5	0.066	0.07		667	
	non noble metal	lead	7439-92-1	3.170	3.19	3.34	31865	33366
heatspreader	non noble metal	copper	7440-50-8	0.000	0.00		1	
	non noble metal	iron	7439-89-6	0.000	0.00		1	
	inorganic material	phosphorus	7723-14-0	0.000	0.00	0.00	1	0
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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